

### Features

- DC – 4.0 GHz
- 20 Watts
- Aluminum Nitride (AlN) Ceramic
- Welded Silver Leads
- Non-Nichrome Resistive Element
- Low VSWR
- 100% Tested

### General Specifications

<b>Resistive Element:</b>	Thick film
<b>Substrate:</b>	Aluminum nitride ceramic
<b>Cover:</b>	Alumina ceramic
<b>Mounting Flange:</b>	Copper, nickel plated per QQ-N-290
<b>Lead(s):</b>	99.99% pure silver (.005" thk)

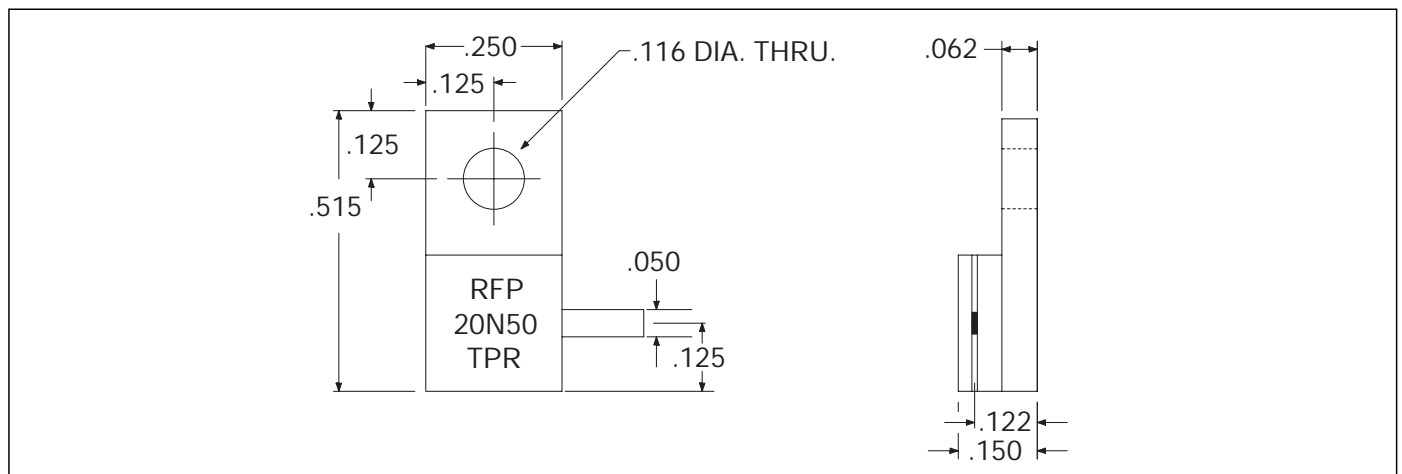
### Electrical Specifications

<b>Resistance Value:</b>	50 ohms, ±5%
<b>Frequency Range:</b>	DC - 4.0 GHz
<b>Power:</b>	20 Watts
<b>V.S.W.R.:</b>	1.25:1

**Notes:** Tolerance is ±.010, unless otherwise specified. Operating temperature is -55°C to +150°C (see chart). Designed to meet or exceed applicable portions of MIL-E-5400. All dimensions are in inches. Lead length 0.15" minimum.

**Specifications subject to change without notice.**

### Outline Drawing



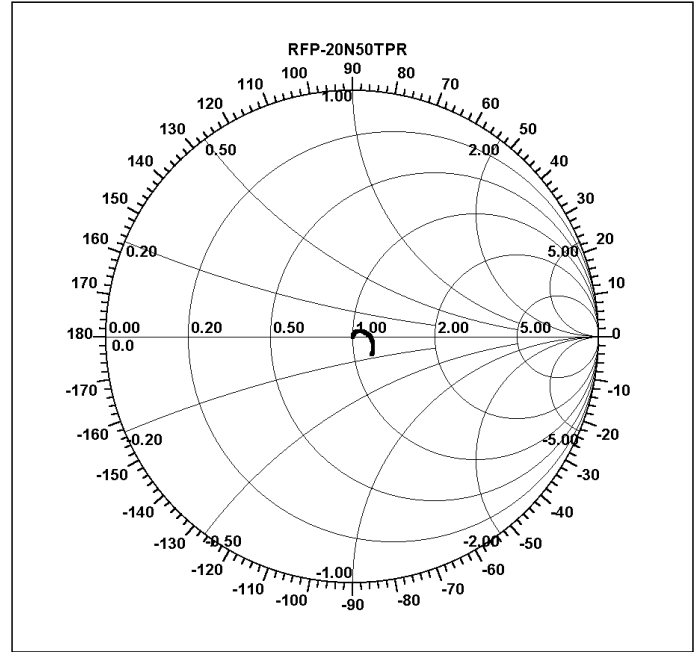
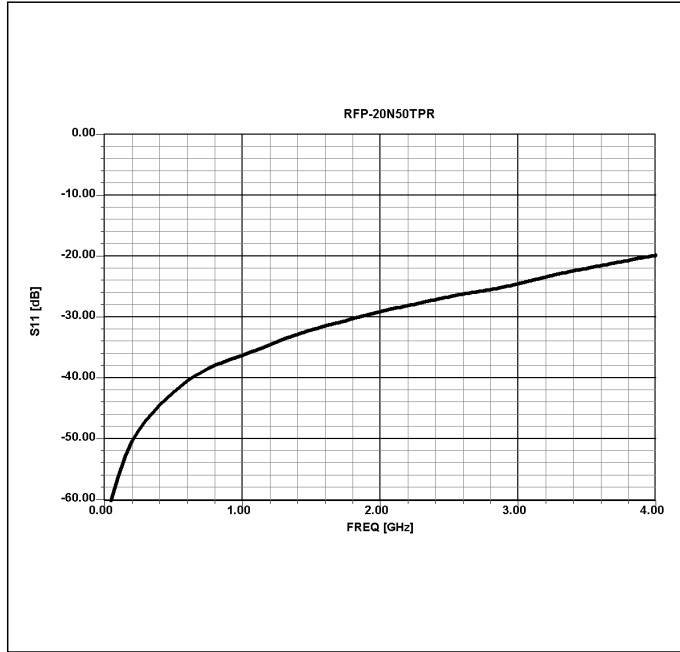
VER. 12/5/01

# Model RFP-20N50TPR

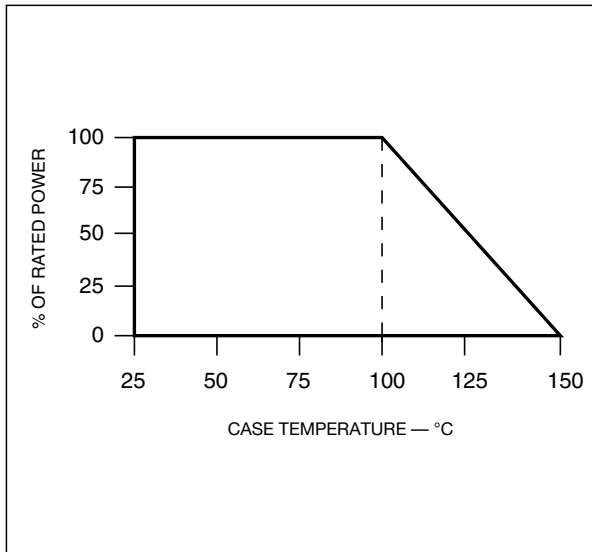


**RF Power**

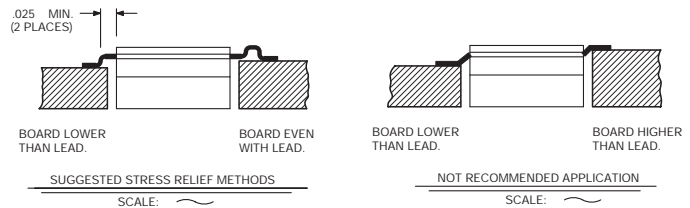
## Typical Performance



## Power Derating



## Suggested Mounting Procedures



1. Make sure that the devices are mounted on flat surfaces (.001" under the device) to optimize the heat transfer.
2. Drill & tap the heatsink for the appropriate thread size to be used.
3. Coat heatsink with a minimum amount of high quality silicone grease (.001" max. thickness).
4. Position device on mounting surface & secure using socket head screws, flat & split washers. Torque screws to the appropriate value. Make sure that the device is flat against the heatsink. (Care should be taken to avoid upward pressure of the leads towards the lid).
5. Solder leads in place using an SN63 type solder with a controlled temperature iron (700°F).